1 1

FIG.1

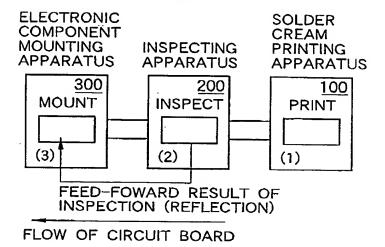
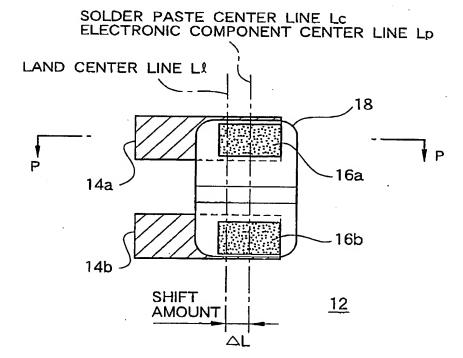
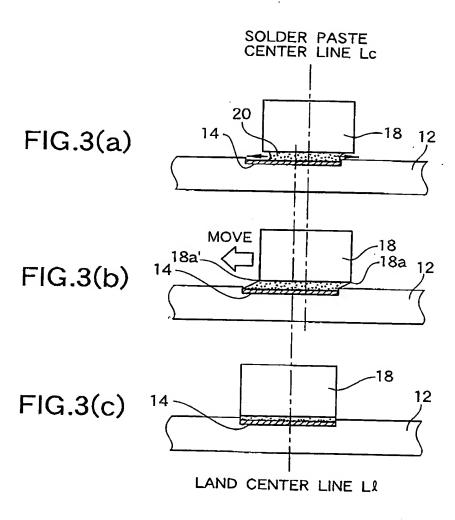
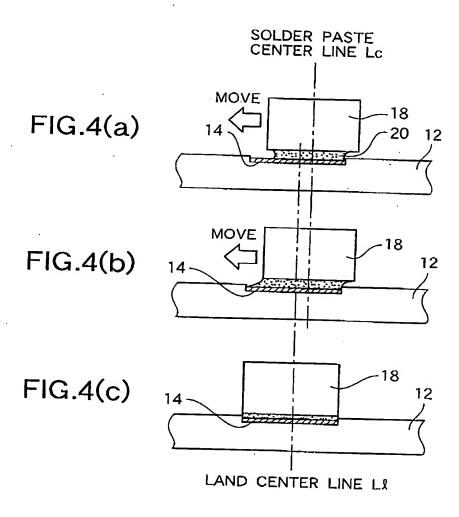


FIG.2







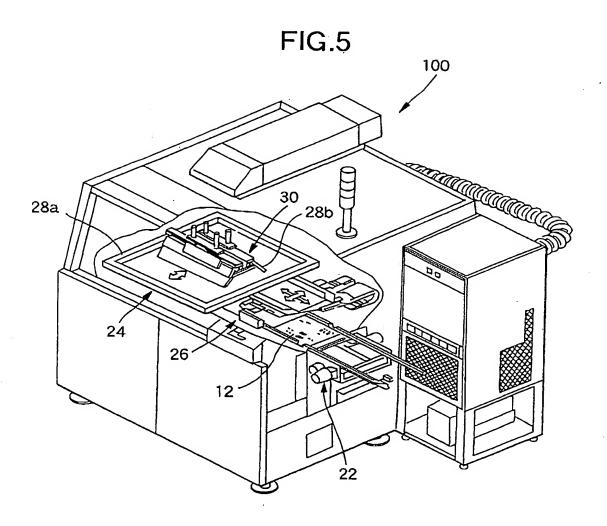
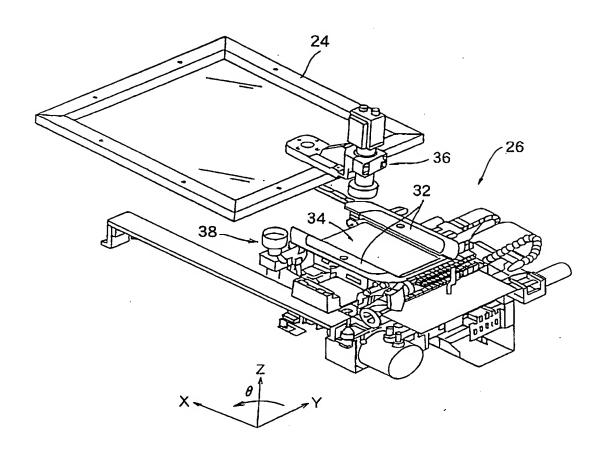
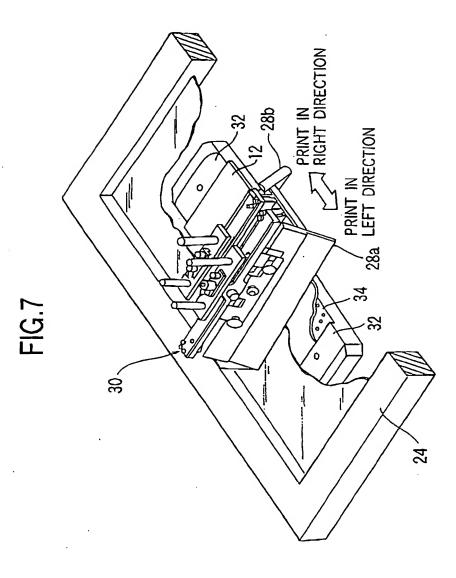
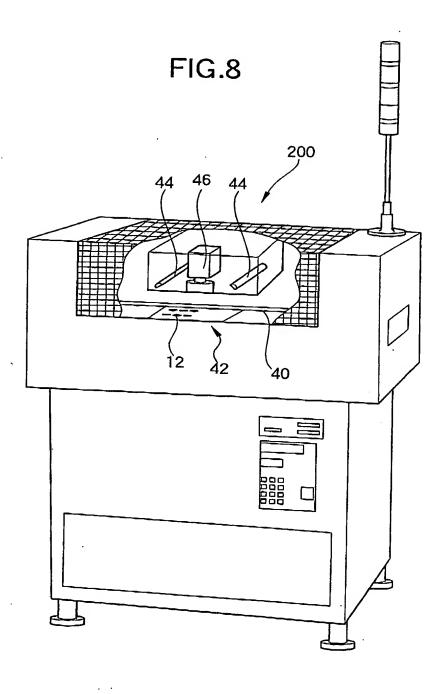


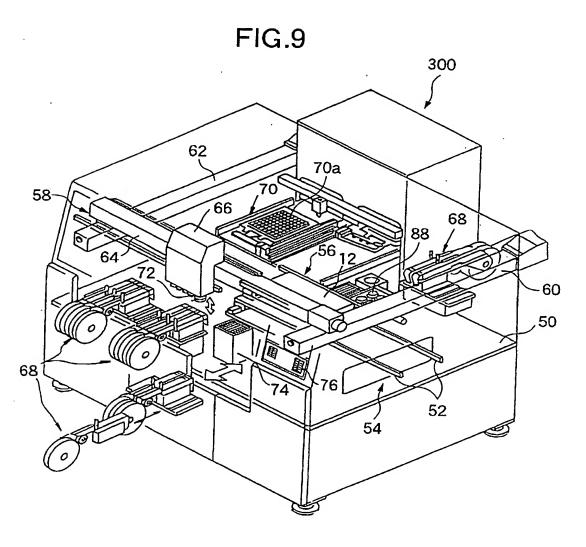
FIG.6

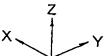


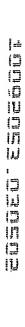




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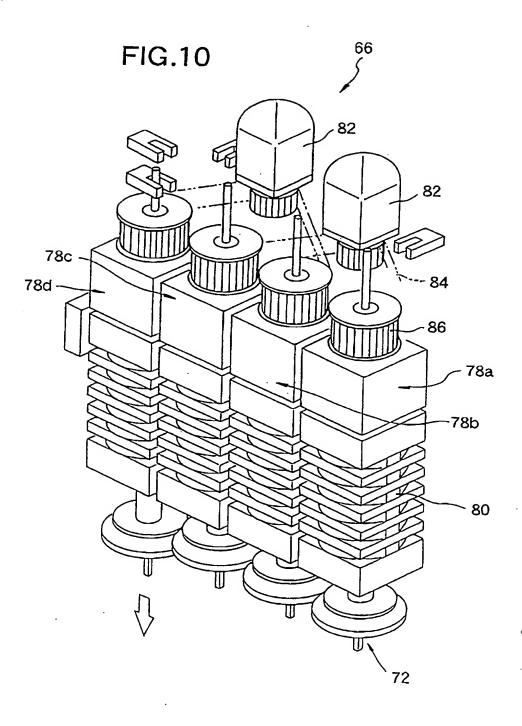


FIG.11

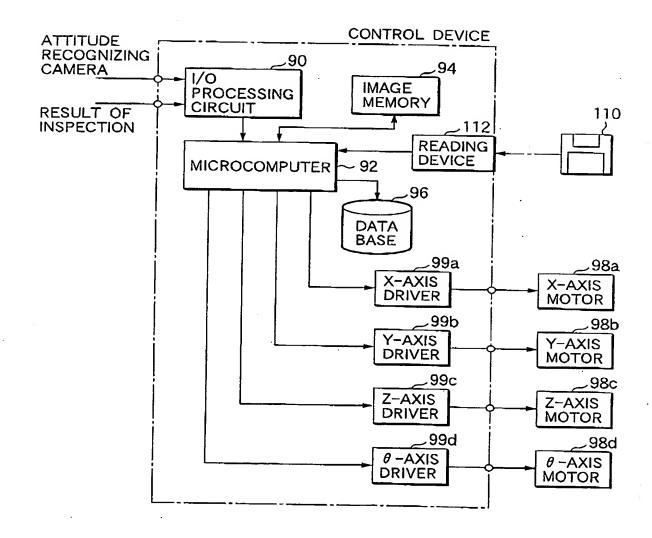
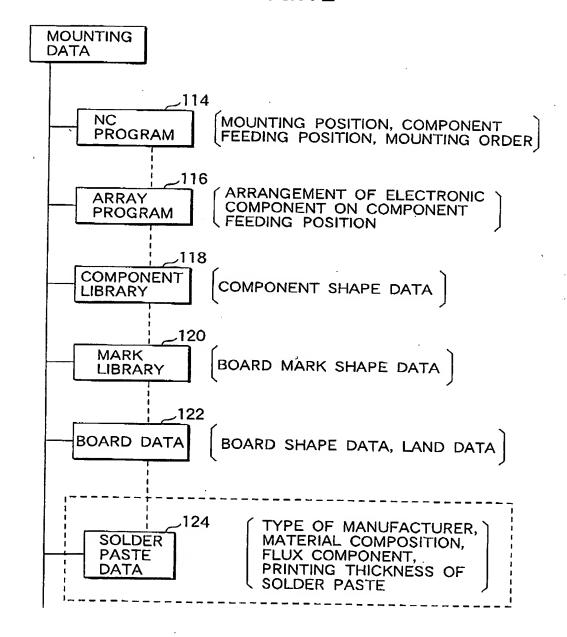


FIG.12



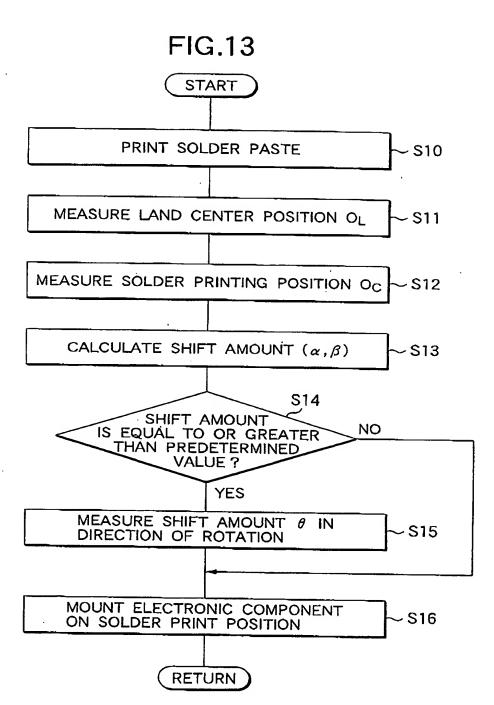
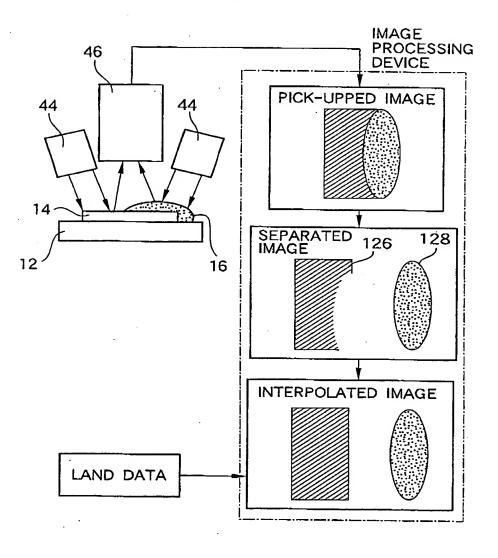
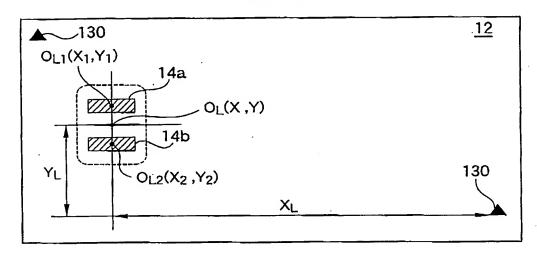


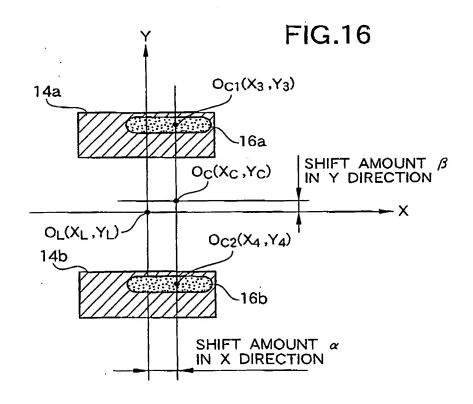
FIG.14



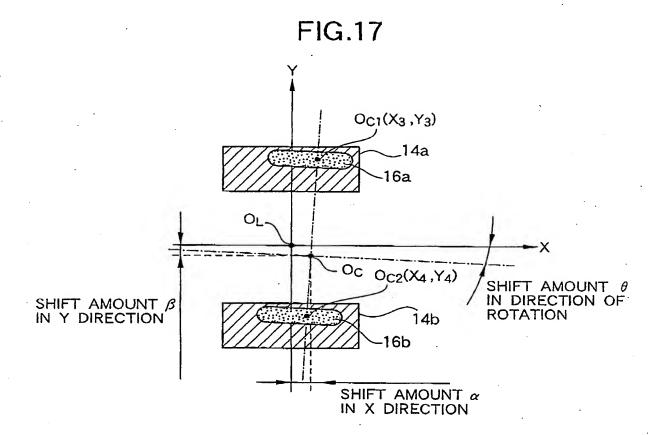
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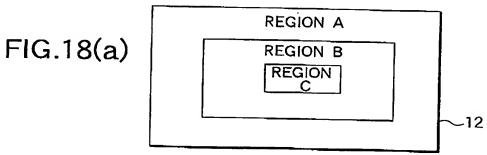
FIG.15











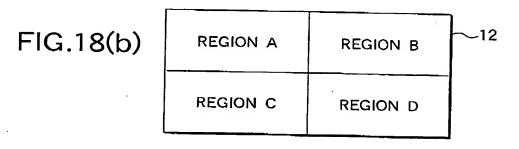
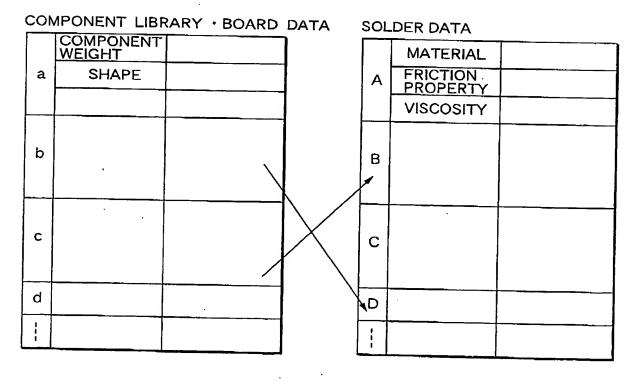


FIG.19



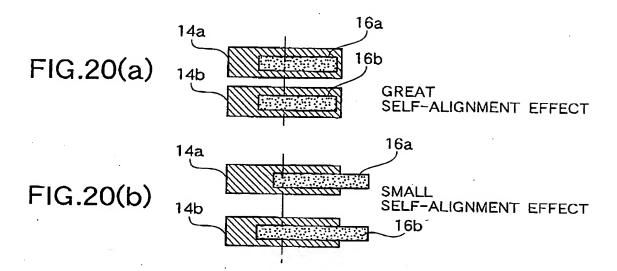
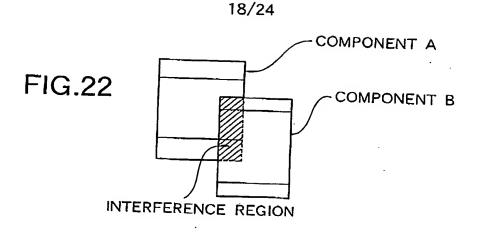
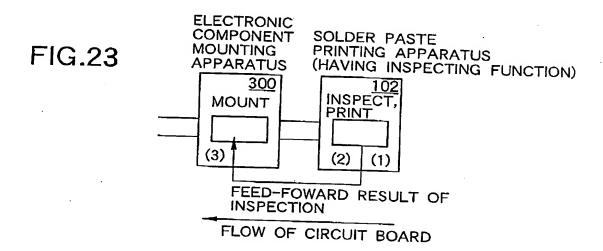


FIG.21 START RECOGNIZE LAND POSITION AND SHAPE **S20** RECOGNIZE SOLDER PRINT POSITION AND - S21 SHAPE **S22** SELF-ALIGNMENT NO RATIO IS HIGH? YES **S23** S24 MOUNT ELECTRONIC MOUNT ELECTRONIC COMPONENT IN LAND COMPONENT IN SOLDER PRINT POSITION **POSITION RETURN**





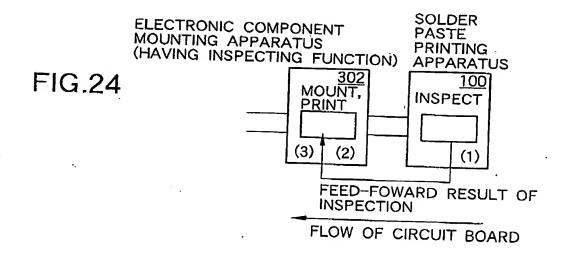
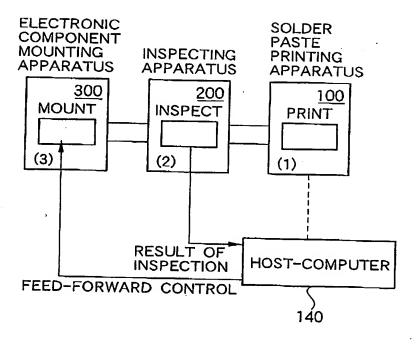


FIG.25



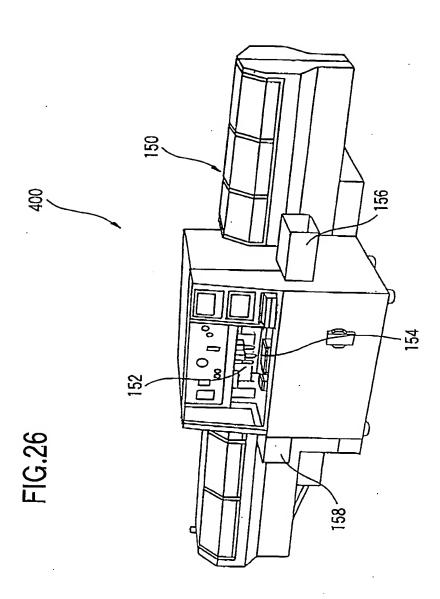
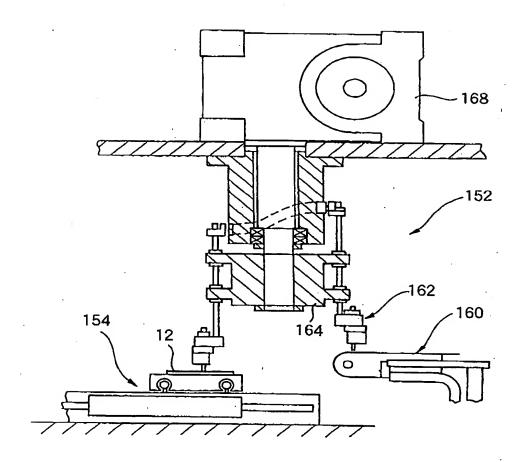


FIG.27



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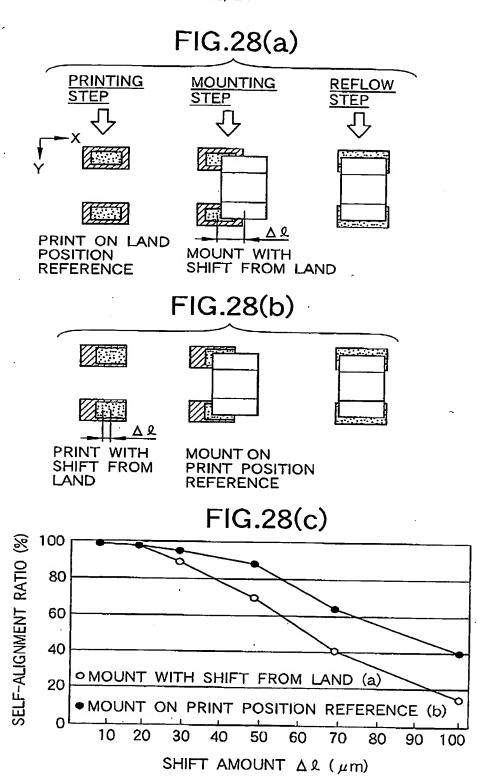
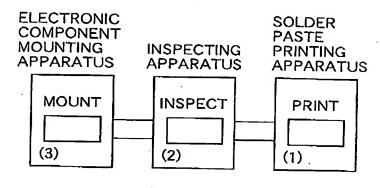


FIG.29



FLOW OF CIRCUIT BOARD

FIG.30(a)

FIG.30(b)

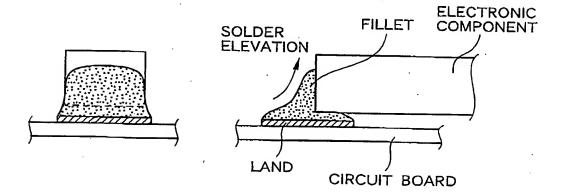


FIG.31(a)

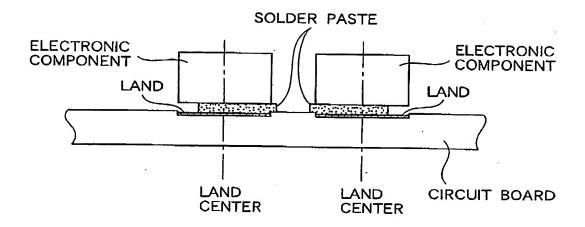


FIG.31(b)

